

PROCESSING APPARATUS

ABSTRACT

A processing apparatus includes a holding unit, a processing unit, and an imaging unit that is disposed over the holding unit and images an outer circumferential part of a wafer. The imaging unit has a camera part, a light emitting unit including a light source, and at least three reflecting units that each allow light from the light source to be output upward. By adjustment of the position of each reflecting unit in the imaging unit, the outer circumferential part of the wafer that has a larger diameter than the holding table and sticks out to the outside of the holding table in the radial direction when being held under suction by the holding table is irradiated with the light from the light source sequentially from each reflecting unit, and at least three places in the outer circumferential part of the wafer are imaged by the imaging unit.

[FIG. 1]